

ABSTRACT

WIRE BONDING APPARATUS

A wire bonding apparatus for connecting an electrode of a semiconductor chip (43) to a lead of a lead frame using a wire or bonding a bump to a pad of a semiconductor chip comprises DC pulse applying means for
5 applying DC pulse to the wire or the bump, detection means for detecting a response waveform from the wire or the bump applied with the DC pulse, and discrimination means for discriminating whether or not the wire or the
10 bump is successfully bonding-connected by comparing the response waveform with an unsuccessful bonding response waveform obtained by applying the DC pulse to an unsuccessfully bonded wire or bump.